

Title (en)
SEMICONDUCTOR DEVICE AND METHOD FOR MANUFACTURING SEMICONDUCTOR DEVICE

Title (de)
HALBLEITERBAUELEMENT UND HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)
DISPOSITIF À SEMI-CONDUCTEURS ET SON PROCÉDÉ DE FABRICATION

Publication
EP 2457256 A4 20150729 (EN)

Application
EP 10802163 A 20100625

Priority
• JP 2009169599 A 20090718
• JP 2010061299 W 20100625

Abstract (en)
[origin: US2011012112A1] An aperture ratio of a semiconductor device is improved. A driver circuit and a pixel are provided over one substrate, and a first thin film transistor in the driver circuit and a second thin film transistor in the pixel each include a gate electrode layer, a gate insulating layer over the gate electrode layer, an oxide semiconductor layer over the gate insulating layer, source and drain electrode layers over the oxide semiconductor layer, and an oxide insulating layer in contact with part of the oxide semiconductor layer over the gate insulating layer, the oxide semiconductor layer, and the source and drain electrode layers. The gate electrode layer, the gate insulating layer, the oxide semiconductor layer, the source and drain electrode layers, and the oxide insulating layer of the second thin film transistor each have a light-transmitting property.

IPC 8 full level
H01L 29/786 (2006.01); **G02F 1/1368** (2006.01); **G09F 9/30** (2006.01); **H01L 21/02** (2006.01); **H01L 21/28** (2006.01); **H01L 21/336** (2006.01); **H01L 27/12** (2006.01); **H01L 29/45** (2006.01); **H05B 44/00** (2022.01)

CPC (source: EP KR US)
G02F 1/1368 (2013.01 - US); **H01L 21/02554** (2013.01 - KR); **H01L 21/02565** (2013.01 - KR); **H01L 27/1214** (2013.01 - KR); **H01L 27/1225** (2013.01 - EP KR US); **H01L 27/124** (2013.01 - EP US); **H01L 27/1248** (2013.01 - KR); **H01L 27/1251** (2013.01 - EP US); **H01L 27/1255** (2013.01 - EP US); **H01L 29/45** (2013.01 - EP KR US); **H01L 29/78606** (2013.01 - KR); **H01L 29/78645** (2013.01 - US); **H01L 29/78648** (2013.01 - KR); **H01L 21/02554** (2013.01 - EP US); **H01L 21/02565** (2013.01 - EP US)

Citation (search report)
• [I] US 2008284933 A1 20081120 - ITO MANABU [JP], et al
• [A] US 2004038446 A1 20040226 - TAKEDA KATSUTOSHI [JP], et al

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Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO SE SI SK SM TR

DOCDB simple family (publication)
US 2011012112 A1 20110120; US 8552423 B2 20131008; CN 102576732 A 20120711; CN 102576732 B 20150225; CN 102751295 A 20121024; CN 102751295 B 20150715; EP 2457256 A1 20120530; EP 2457256 A4 20150729; EP 2457256 B1 20200617; JP 2011044699 A 20110303; JP 2014132660 A 20140717; JP 2015159290 A 20150903; JP 2017050550 A 20170309; JP 2018186273 A 20181122; JP 2019149555 A 20190905; JP 2021100124 A 20210701; JP 2023015041 A 20230131; JP 5455825 B2 20140326; JP 5714141 B2 20150507; JP 6030171 B2 20161124; JP 6339151 B2 20180606; JP 6506445 B2 20190424; KR 101414926 B1 20140704; KR 101851403 B1 20180423; KR 101907366 B1 20181011; KR 102181301 B1 20201120; KR 20120117723 A 20121024; KR 20120123157 A 20121107; KR 20180042450 A 20180425; KR 20180112107 A 20181011; KR 20190112846 A 20191007; TW 201123422 A 20110701; TW 201250988 A 20121216; TW 201519409 A 20150516; TW 201707191 A 20170216; TW 201832348 A 20180901; TW 202018909 A 20200516; TW 202115868 A 20210416; TW I472016 B 20150201; TW I481010 B 20150411; TW I557879 B 20161111; TW I644414 B 20181211; TW I693696 B 20200511; US 10461098 B2 20191029; US 11177289 B2 20211116; US 11715741 B2 20230801; US 2012300151 A1 20121129; US 2014293183 A1 20141002; US 2016118417 A1 20160428; US 2020058682 A1 20200220; US 2022068977 A1 20220303; US 8698143 B2 20140415; US 9263472 B2 20160216; WO 2011010543 A1 20110127

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US 83590310 A 20100714; CN 201080019588 A 20100625; CN 201210271486 A 20100625; EP 10802163 A 20100625; JP 2010061299 W 20100625; JP 2010160035 A 20100714; JP 2014000899 A 20140107; JP 2015047079 A 20150310; JP 2016204942 A 20161019; JP 2018090453 A 20180509; JP 2019063819 A 20190328; JP 2021018094 A 20210208; JP 2022163024 A 20221011; KR 20127004265 A 20100625; KR 20127026398 A 20100625; KR 20187010460 A 20100625; KR 20187028509 A 20100625; KR 20197028282 A 20100625; TW 101126952 A 20100712; TW 103140636 A 20100712; TW 105127069 A 20100712; TW 107101090 A 20100712; TW 108127709 A 20100712; TW 109130016 A 20100712; TW 99122831 A 20100712; US 201213567327 A 20120806; US 201414244440 A 20140403; US 201514986156 A 20151231; US 201916662394 A 20191024; US 202117512855 A 20211028